



RD Number: RD181

RD Title: TB67B000AHG Evaluation Circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	IC1	1	TB67B000AHG	TB67B000AHG	TOSHIBA	Brushless Motor Driver	DIP30	
2	R1	1	68k Ω	--	--	Resistor		
3	R1A	0	Not mount	--	--			✓
4	R2	1	Lead jumper	--	--	Short with jumper wire		
5	R3	1	0.51 Ω	--	--	Resistor		
6	R3A	0	Not mount	--	--			✓
7	R4	0	Not mount	--	--			✓
8	R5	0	Not mount	--	--			✓
9	R6	0	Not mount	--	--			✓
10	R7	0	Not mount	--	--			✓
11	R8	0	Not mount	--	--			✓
12	R9	0	Not mount	--	--			✓
13	R10	0	Not mount	--	--			✓
14	R11	0	Not mount	--	--			✓
15	R12	0	Not mount	--	--			✓
16	R13	0	Not mount	--	--			✓
17	C1	1	0.01 μ F	--	--	Capacitor		
18	C2	1	0.1 μ F	--	--	Capacitor		
19	C3	1	1 μ F 50V	--	--	Capacitor		
20	C4	1	0.001 μ F	--	--	Capacitor		
21	C5	0	Not mount	--	--			✓
22	C6	1	10 μ F 50V	--	--	Capacitor		
23	C7	1	0.1 μ F	--	--	Capacitor		
24	C8	1	2.2 μ F 50V	--	--	Capacitor		
25	C9	1	2.2 μ F 50V	--	--	Capacitor		
26	C10	1	2.2 μ F 50V	--	--	Capacitor		
27	C11	1	0.1 μ F	--	--	Capacitor		
28	C12	1	0.1 μ F	--	--	Capacitor		
29	C13	1	0.1 μ F	--	--	Capacitor		
30	C14	0	Not mount	--	--			✓
31	C15	0	Not mount	--	--			✓
32	C16	0	Not mount	--	--			✓
33	C17	0	Not mount	--	--			✓
34	C18	0	Not mount	--	--			✓

35	C19	0	Not mount	-	-		✓
36	C20	0	Not mount	-	-		✓
37	C21	0	Not mount	-	-		✓
38	C22	0	Not mount	-	-		✓
39	SW1	1	Toggle switch	-	-	Toggle switch	
40	SW2	1	Toggle switch	-	-	Toggle switch	
41	SW3	1	Toggle switch	-	-	Toggle switch	
42	JP1	0	Not mount	-	-		✓
43	JP2	0	Not mount	-	-		✓
44	JP3	0	Not mount	-	-		✓
45	JP4	0	Not mount	-	-		✓
46	JP5	2	Short with solder	-	-	Short slit land with solder	
47	JP6	2	Short with solder	-	-	Short slit land with solder	
48	JP7	2	Short with solder	-	-	Short slit land with solder	
49	JP8	0	Not mount	-	-		✓
50	JP9	0	Not mount	-	-		✓
51	JP10	0	Not mount	-	-		✓
52	JP	15	Short with solder	-	-	Short slit land with solder	
53	U	1	Check terminal	-	-	Metal post	
54	V	1	Check terminal	-	-	Metal post	
55	W	1	Check terminal	-	-	Metal post	
56	VBB	1	Check terminal	-	-	Metal post	
57	PGND1	1	Check terminal	-	-	Metal post	
58	VCC	1	Check terminal	-	-	Metal post	
59	SGND1	1	Check terminal	-	-	Metal post	
60	FG	1	Check terminal	-	-	Metal post	
61	VSP	1	Check terminal	-	-	Metal post	
62	LA	1	Check terminal	-	-	Metal post	
63	SGND2	1	Check terminal	-	-	Metal post	
64	HU	1	Check terminal	-	-	Metal post	
65	HV	1	Check terminal	-	-	Metal post	
66	HW	1	Check terminal	-	-	Metal post	
67	VREFOUT2	1	Check terminal	-	-	Metal post	
68	SGND3	1	Check terminal	-	-	Metal post	
69	HUP	1	Check terminal	-	-	Metal post	
70	HUM	1	Check terminal	-	-	Metal post	
71	HVP	1	Check terminal	-	-	Metal post	
72	HVM	1	Check terminal	-	-	Metal post	
73	HWP	1	Check terminal	-	-	Metal post	
74	HWM	1	Check terminal	-	-	Metal post	
75	VREFOUT1	1	Check terminal	-	-	Metal post	
76	FGC	1	Check terminal	-	-	Metal post	
77	SS	1	Check terminal	-	-	Metal post	

78	CW/CCW	1	Check terminal	-	-	Metal post		
79	SGND4	1	Check terminal	-	-	Metal post		
80	IDC	1	Check terminal	-	-	Metal post		
81	PGND2	1	Check terminal	-	-	Metal post		

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